

4

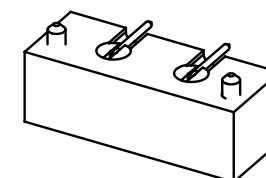
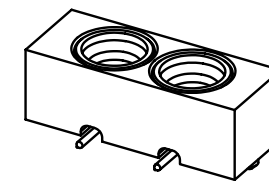
3

2

1

PART NO.	INTERFACE
-1CC	LIMITED DETENT
-2CC	SMOOTH BORE

REVISIONS			
REV.	DESCRIPTION	DATE	BY
-	INITIAL RELEASE	2/14/2013	YP



SSMP® is a registered trademark of Carlisle IT.

MATERIAL(S):	ELECTRICAL(S):	MECHANICAL(S):	ENVIRONMENTAL(S):
Block & Center Conductor: Brass Alloy C360 per ASTM B-16 Insert: 303 SST per ASTM A-582 Insulator: Polyamide-Imide per ASTM D-5204 or MIL-P-46179 Dowel Pins: 18-8 Stainless Steel	Impedance: 50 Ohms Nominal Frequency Range: DC to 40 GHz VSWR: 1.15:1 to 26.5 GHz Typ. 1.30:1 to 40 GHz Typ. Insertion Loss: $.04 \times \sqrt{f}$ (GHz) dB Working Voltage: 125 Vrms max @ Sea Level Dielectric Withstand Voltage: 325 Vrms min. RF HiPot Voltage: 150 Vrms min. @ 5MHz Corona Level: 125 Vrms @ 70,000 ft Insulation Resistance: 5000 MegOhms min. Contact Resistance: Center Contact: 6.0 Milliohms max	Interface Dimensions: Carlisle IT WS134 Connector Durability: 100 Cycles min. for Detent 500 Cycles min. for Smooth Bore Force to Engage: Detent: 6.5 lbs max Smooth Bore: 2.5 lbs max Force to Disengage: Detent: 4 lbs min 1.5 lbs Disengage min	Temperature Range: -65°C to +165°C Thermal Shock: MIL-STD-202, Method 107, Test Condition B Moisture Resistance: MIL-STD-202, Method 106, Insulation resistance at least 200 MegaOhms within 5 minutes after removal from humidity. Corrosion: MIL-STD-202, Method 101, Test Condition B Vibration: MIL-STD-202, Method 204, Test Condition D Shock: MIL-STD-202, Method 213, Test Condition I

FINISH(ES):			APPLICABLE CARLISLE IT DOCUMENTS			TOLERANCES AND NOTES EXCEPT AS NOTED								
Block & Center Conductor: Sulfamate nickel plate per SAE-AMS-QQ-N-290, Class 1, followed by Gold plate per MIL-DTL-45204, type II, Grade C.  Insert & Dowel Pins: Passivate per ASTM A-967			WORK STANDARD	PROD INSTRUC	ASSY INSTRUC	DIMENSIONS ARE IN INCHES. XX ±.015 ANGULAR ± 1/2° LINEAR .XXX ±.005 ANGULAR ± 1/2° FRACTION ± 1/32								
			NA	NA	NA									
			-			1. MACHINE FINISH: $\sqrt{\text{RMS}}$								
						2. BREAK ALL SHARP EDGES .003 MAX.								
			NOTICE THIS DRAWING EMBODIES A CONFIDENTIAL PROPRIETARY DESIGN ORIGINATED BY CARLISLE INTERCONNECT TECHNOLOGIES & ALL DESIGN, MANUFACTURING, PRODUCTION, USE & SALE RESTRICTED REGARDING THE SAME ARE EXPRESSLY RESERVED. IT IS SUBMITTED UNDER A CONFIDENTIAL RELATIONSHIP FOR A SPECIFIED PURPOSE & THE RECIPIENT AGREES BY ACCEPTING THIS DRAWING NOT SUPPLY OR DISCLOSE ANY INFORMATION REGARDING IT TO ANY UNAUTHORIZED PERSON OR TO INCORPORATE OTHER PROJECTS. SPECIAL FEATURES PECULIAR TO THIS DESIGN. ALL PATENT RIGHTS HERETO ARE EXPRESSLY RESERVED BY CARLISLE INTERCONNECT TECHNOLOGIES, CERRITOS, CALIFORNIA 90703.											
						3. MACHINED FILLETS .005 MAX.								
						4. MACHINED SURFACES SQUARE TO RESPECTIVE AXIS WITHIN .005 INCHES PER INCH.								
						5. MACHINED DIAMETERS CONCENTRIC WITHIN .002 T.I.R.								
						6. DIMENSIONS TO BE MET BEFORE PLATING.								
						7. CHAMFER ALL THREADS 45°.								
						8. THREADS PER H-28								
						9. REMOVE FRAVED EDGES ON TEFLON.								
						10. REMOVE ALL BURRS.								

4

3

2

1

A wide variety of transmission line analysis & PCB board parameters like permittivity, substrate thickness, & board stackup are applied by the customer. These parameters have a impact on the RF performance of the device.  
\*This layout is not optimised to fit all board config's regarding RF performance, it represents a recommendation for optimum solderability of the device.  
To guarantee high RF performance of the device, an RF analysis of the device to the board transision is recommended.

SURFACE MOUNTING PATTERN  
(TOP VIEW)

